

IN THE SPECIFICATION

Please replace the Abstract beginning at page 23, line 2 with the following rewritten paragraph:

~~A compliant wafer chuck for supporting a substrate in which an upper body of the chuck is allowed to tilt relative to the base.~~ A method of processing a wafer includes placing a wafer atop a wafer chuck, wherein the chuck has a base and an upper body in which the upper body is coupled to the base by a flexible coupling that allows the upper body to tilt relative to the base. The wafer is engaged to a hollow sleeve and forms a floor creating an enclosed vessel to retain a processing fluid. Once the vessel is filled, the wafer is then processed utilizing the processing fluid. Further, the wafer tilts allowing for a compliant engagement of the wafer and the sleeve to prevent or reduce leakage of the processing fluid.